



SOT370-1

plastic shrink small outline package; 48 leads; body width 7.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP48
Package type industry code	SSOP48
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-118
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

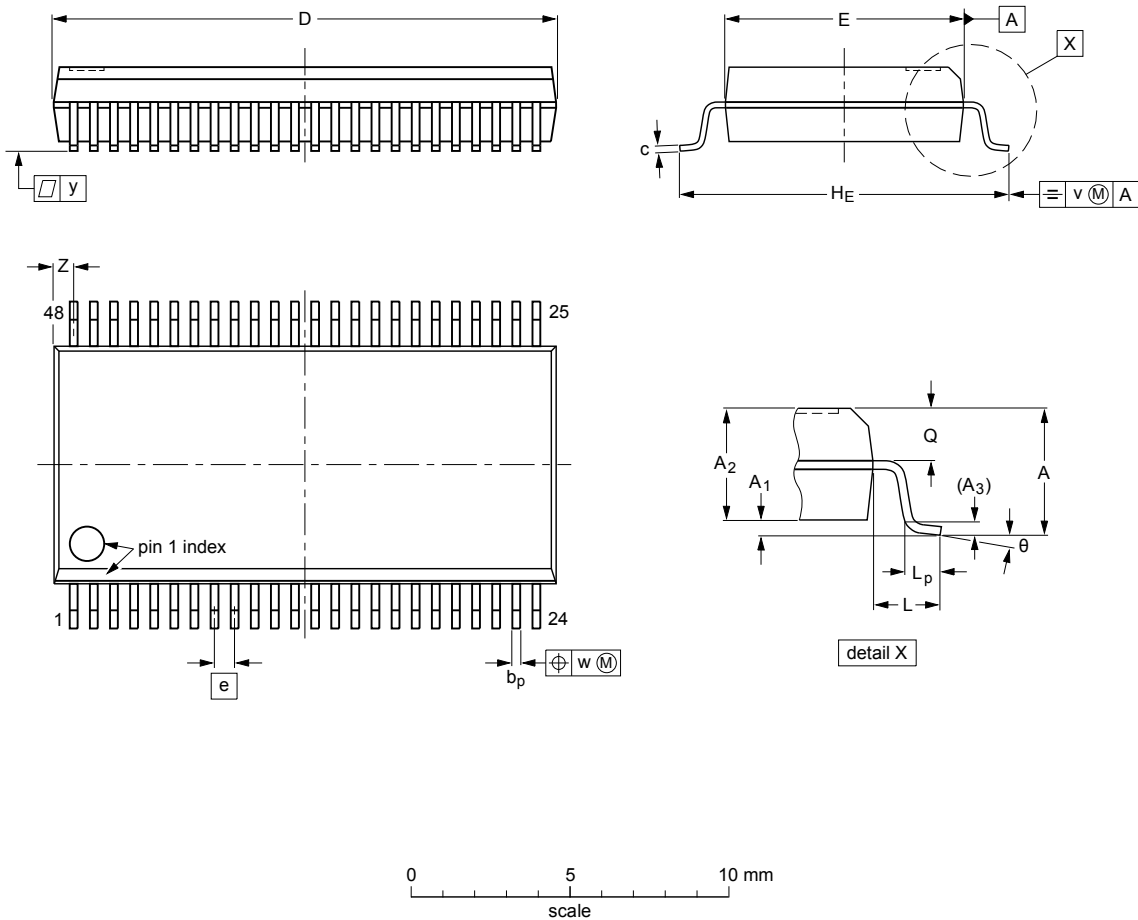
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.75	-	15.9	16	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	[tbd]	-	2.8	2.8	mm
A ₂	package height	2.2	-	2.3	2.35	mm
n ₂	actual quantity of termination	-	-	48	-	



2. Package outline

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	16.00 15.75	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT370-1		MO-118				99-12-27 03-02-19

Fig. 1. Package outline SSOP48 (SOT370-1)

3. Soldering

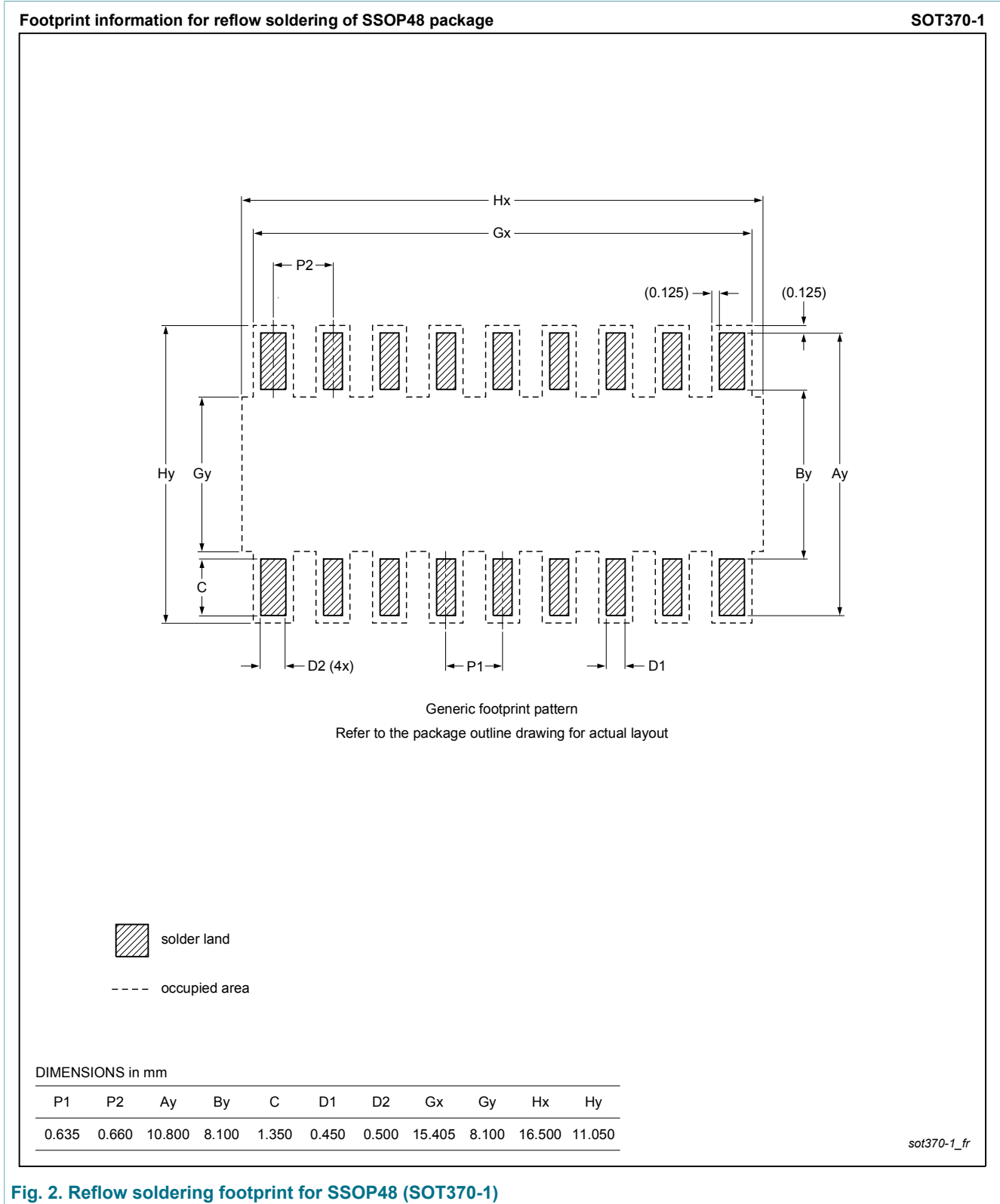


Fig. 2. Reflow soldering footprint for SSOP48 (SOT370-1)

4. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com

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